OUTPUTS



Data sheet acquired from Harris Semiconductor SCHS100

CMOS Decade Up-Down Counter/Latch/Display Driver

High-Voltage Type (20-V Rating)





Features:

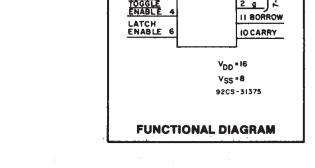
- Separate clock-up and clock-down lines-
- Capable of driving common cathode LEDs and other displays directly
- Allows cascading without any external circuitry
- 100% tested for quiescent current at 20 V
- Maximum input current of 1 μA at 18 V over full packagetemperature range; 100 nA at 18 V and 25° C

■ CD40110B is a dual_clocked up/down counter with a special preconditioning circuit that allows the counter to be clocked, via positive going inputs, up or down regardless of the state or timing (within 100 ns typ.) of the other clock line.

The clock signal is fed into the control logic and Johnson counter after it is preconditioned. The outputs of the Johnson counter (which include anti-lock gating to avoid being locked at an illegal state) are fed into a latch. This data can be fed directly to the decoder through the latch or can be strobed to hold a particular count while the Johnson counter continues to be clocked. The decoder feeds a seven-segment bipolar output driver which can source up to 25 mA to drive LEDs and other displays such as low-voltage fluorescent and incandescent lamps.

A short durating negative-going pulse appears on the BORROW output when the count changes from 0 to 9 or the CARRY output when the count changes from 9 to 0. At the other times the BORROW and CARRY outputs are a logic 1.

The CARRY and BORROW outputs can be tied directly to the clock-up and clock-down lines respectively of another CD40110B for easy cascading of several counters.



CLK UP

CLK DN

RESET

CD40110B Types

- Noise margin (full package-temperature range) =
 - 1 V at V_{DD} = 5 V
 - 2 V at V_{DD} = 10 V
 - 2.5 V at VDD = 15 V
- 5 V, 10 V and 15 V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices".

Applications:

- Rate comparators
- General counting applications where display is desired
- Up-down counting applications where input pulses are random in nature

The CD40110B types are supplied in 16-lead dual-in-line ceramic packages (D and F suffixes), and 16-lead dual-in-line plastic package (E suffix), and also available in chip form, (H suffix).

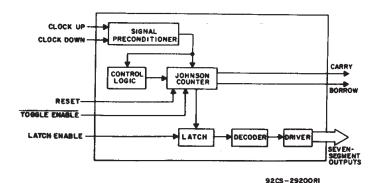


Fig. 1 - Functional diagram.

MAXIMUM RATINGS, Absolute-Maximum Values:	
Voltages referenced to V _{SS} Terminal)	0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS	
DC INPUT CURRENT, ANY ONE INPUT	±10mA
For T _A = -55°C to +100°C	500mW
For T _A = +100°C to +125°C	Derate Linearity at 12mW/°C to 200mW
For T _A = -55°C to +100°C For T _A = +100°C to +125°C DEVICE DISSIPATION PER OUTPUT TRANSISTOR FOR T _A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)	
FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)	100mW
OPERATING-TEMPERATURE RANGE (TA)	55°C to +125°C
STORAGE TEMPERATURE RANGE (Tstg)	-65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):	
STORAGE TEMPERATURE RANGE (T_{stg})	+265°C

RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

C	CHARACTERISTIC	er transport of the second of	V _{DD}	LIM MIN.	ITS MAX.	UNITS
Supply-Voltage Range (For TA =	Full Package Temperatu	ure Range)		3	18	V
Clock Input Frequency (Sum of CLUP & CLDN Freqs.)	foliation of the state of the s	Herrican State of the State of	5 10 15		1 3 5	MHz
Clock Pulse Width tw			5 10 15	110 40 30	111	
Latch Enable Pulse Width	N	100 mm	5 10 15	110 30 24	1 1 1	· Service
Reset Removal-Time		and a light of the control	5 10 15		- -	erre (n. 1900) 1000 - August II. 1900 - August II.
Reset Pulse Width			5 10 15	350 170 120	=	

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STATIC ELECTRICAL CHARACTERISTICS

		Conditions										
Characteristic				V _{DD}	LIMITS AT INDICATED TEMPERATURES (°C)						Units	
	IOH (mA)	Vон (V)	V _{IN} (V)		-55 -40 +85 +125			+25 Min. Typ. Max.		Max.	-	
		` '					450	450			_	···
Quiescent Device				5	5	5	150	150		0.04 0.04	5 10	
Current				10	10	10	300	300		0.04	20	μΑ
Max. I _{DD}	=			15 20	100	20 100	600 3000	600 3000	=	0.04	100	
Output Voltage			0,5	5			.05			0	0.05	
Low-Level			0,10	10			.05			0	∣0.05	V
Max. V _{OŁ}		-	0,15	15		0.	.05			0	0.05	
		<u> </u>	0,5	5	_	_		_	_	4.55		
High-Level Min. VOH	_	_	0,10	10						9.55		V
Min. VOH	_	_	0,15	15			_			14.55		·
<u> </u>		I					_					
Input Low Voltage	_	0.5, 3.8		5	1.5					1.5	v	
Max. VIL		1, 8.8	_	10			3			=	3	V
*	-	1.5, 13.8		15	<u> </u>	 	4				4	
Innut High Voltage		0.5, 3.8		5		3	3.8		3.5	_	l —	
Input High Voltage Min. VIH		1, 8.8	_	10			7		7			V
WING VIE	_	1.5, 13.8	-	15			1		11			
]										
	-			Į I		.9		<u>4</u>	3.9	4.5		
	-5					65		.7	3.7	4.3		
	-10		_	5		55		<u>65</u>	3.65	4.25		1
	-15		=		3.5 3.5 3.45 3.35 3.4 3.3		3.6	4.15				
	-20 -25	 	-				3.45 3,4	3.9				
	-23				8.75 8.85		8.75	9.5				
7-Segment Outputs						45	8.55		8.55	9.3		
Output Drive	-10	 			-					8.5	9.25	
Voltage, High	-15	_	_	10		8.42 8.5 8.4 8.47			8.47		-	V
Min. VOH	-20			†	8.4		8.40		8.45	9.1	 _ -	ŀ
141111. YOH	-25	 		1		.3		25	8.3	9	<u> </u>	
				 		3.8		3.9	13.8	14.5	_	
	-5	<u> </u>	_	Ī	13.65		13.75		13.75	14.35	_	
	-10		_	15		3.6		.72	13.72	14.3		
	-15		_] '3	13	3.6	10	3.7	13.7	14.2		
	-20	_	_]	13	3.6	13	3.6	13.65	14.1		
	-25		·		13	3.3	13	.25	13.3	14.0		
7-Segment Outputs		'		_			A .					
Output Low		0.4	0,5	5	1.28	1.22	0.84	0.72	1	2		
(Sink) Current	<u> </u>	0.5	0, 10	10	3.2	3	2.2	1.8	2.6	5.2		ĺ
Min. IOL	-	1.5	0, 15	15	8.4	8	5.6	4.8	6.8	13.6	_	}
Comme October 1	1				 					- :	1	Ì
Carry Outputs Output Low		0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1		
(Sink) Current		0.5	0, 10	10	1.6	1.5	1.1	0.9	1.3	2.6		mA
Min. IOL	_	1.5	0, 15	15	4.2	4	2.8	2.4	3.4	6.8	_	
Output High	_	4.6	0, 5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1		
(Source) Current		2.5	0, 5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2		ļ
Min. IOH		9.5	0, 10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	_	l
3	_	13.5	0, 15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	-	
Input Current Max. I _{IN}	-	0, 18	0, 18	18	±0.1	±0.1	±1	±1		±10 ⁻⁵	±0.1	μΑ

 $[\]blacksquare$ 0(10 μ A)

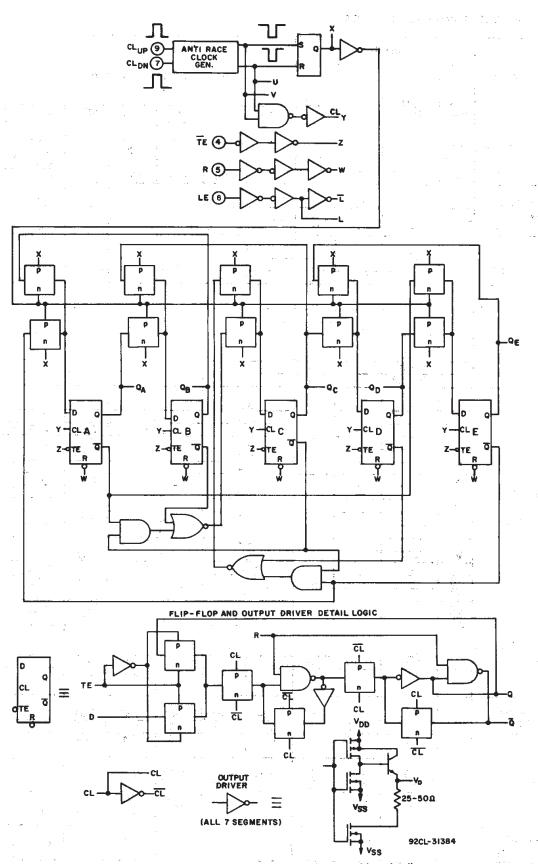


Fig. 2 - Logic diagram with flip-flop and output-driver details. (cont'd on page 5)

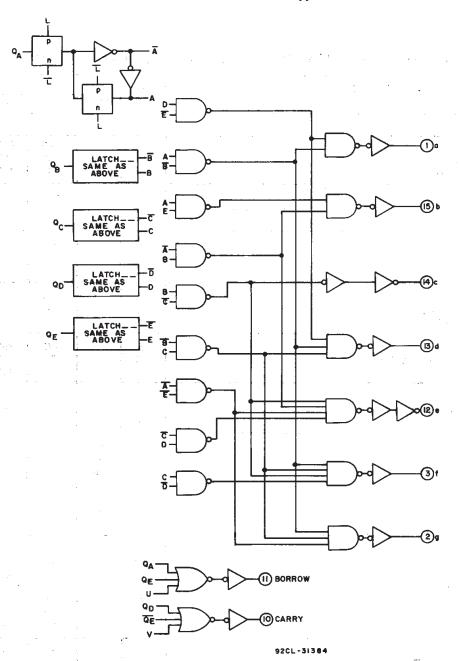
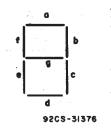
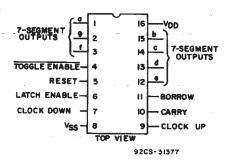


Fig. 2 - Logic diagram with flip-flop and output-driver details.

DISPLAY SEGMENTS



TERMINAL ASSIGNMENT



DYNAMIC ELECTRICAL CHARACTERISTICS at TA = 25° C, input $t_{\rm f}$, $t_{\rm f}$ = 20 ns, CL = 50 pF, RL = 200 k Ω

CHARACTERISTI	C	V _{DD}	MIN.	LIMITS TYP.	MAX.	UNITS		
Clock Up/Clock Down								
Propagation Delay Time: Clock to Carry or Borrow	^t PLH, ^t PHL	5 10 15	<u>-</u> <u>:</u>	300 100 70	600 200 140			
Clock to Segment	tPLH, tPHL	5 10 15	_ 	925 360 250	1850 720 500	ns		
Minimum Clock Pulse Width		5 10 15	_ _ _	55 20 15	110 40 30			
Maximum Clock Input Frequency (Sum of CLup & CLDN F)	fcL	5 10 15	1 3 5	2.5 6 8.5	_ _ _	MHz		
Minimum Toggle Enable Pulse Width		5 10 15	_ 	175 75 55	350 150 110			
Minimum Latch Enable Pulse Width		5 10 15	_ _ _	55 15 12	110 30 24			
Output Pulse Width: Carry		5 10 15	115 60 40	230 120 75	_			
Borrow		5 10 15	140 65 45	275 130 85		ns		
Transition Time: Carry or Borrow	tTLH, tTHL	5 10 15	_ _ _	85 45 30	170 90 60			
Minimum Delay Time Between CLUP & CLDN		5 10 15	_ _	100 80 60	_ _ _			
Maximum Clock Rise or Fall Time	t _r CL, t _f CL	5 10 15	<u>-</u> -	<u>-</u>	15 15 15	μs		
Reset								
Propagation Delay Time Reset to Output	tPLH, tPHL	5 10 15	-	650 350 160	1300 700 320			
Minimum Reset Removal Time	·	5 10 15	_ _ _	-275 -100 -65	0 0 0	ns		
Minimum Reset Pulse Width		5 10 15		175 85 60	350 170 120			

TRUTH TABLE

CLOCK UP*	CLOCK DOWN *	LATCH ENABLE	TOGGLE ENABLE	RESET	COUNTER	DISPLAY
	x	0	0	0	Increments by 1	Follows Counter
Х		0	0	0	Decrements by 1	Follows Counter
		×	X	0	No Change	No Change
X	X	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	×	1	Goes to 00000	Remains Fixed
X	×	0	х	1 (\$4.75)	Goes to 00000	Follows Counter (Display = 1/7)
. X .	X	х	1	0	Inhibited	Remains Fixed
	х	1	0	0	Increments by 1	Remains Fixed
. X		1	0	0	Decrements by 1	Remains Fixed

X = Don't Care

^{*} Typically 100 ns between clock-up and clock-down positive transitions are required to ensure proper counting.

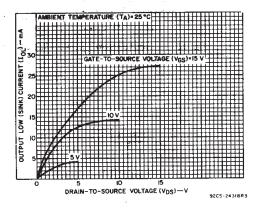


Fig. 3 - Typical carry or borrow output low (sink) current characteristics.

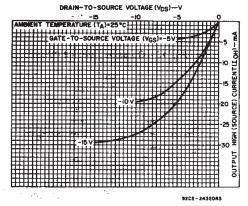


Fig. 5 - Typical carry or borrow output high (source) current characteristics.

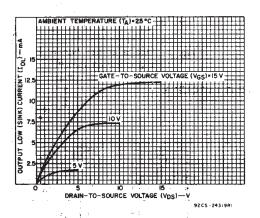


Fig. 4 - Minimum carry or borrow output low (sink) current characteristics.

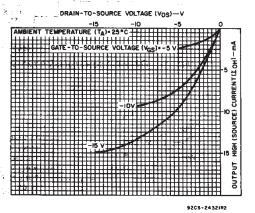


Fig. 6 - Minimum carry or borrow output high (source) current characteristics.

^{1 =} High State

^{0 =} Low State

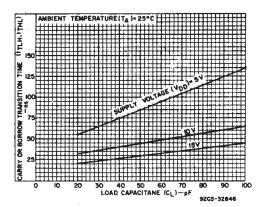


Fig. 7 - Typical carry or borrow transition time vs. load capacitance.

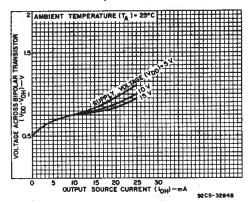


Fig. 9 - Voltage across bipolar transistor vs. output source current.

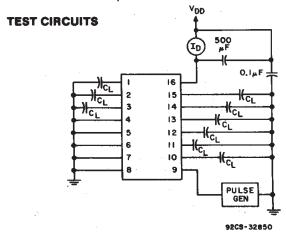


Fig. 11 - Dynamic power dissipation test circuit.

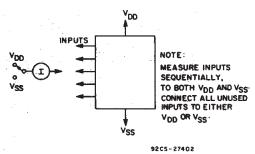


Fig. 13 - Input current.

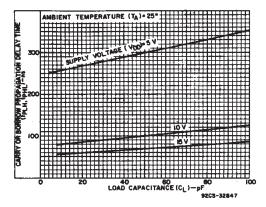


Fig. 8 - Typical carry or borrow propagation delay time vs. load capacitance.

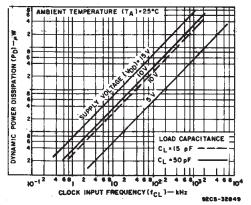


Fig. 10 - Typical dynamic power dissipation vs. frequency.

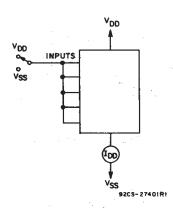


Fig. 12 - Quiescent device current.

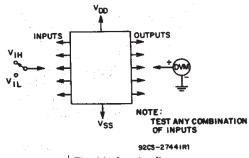


Fig. 14 - Input voltage.

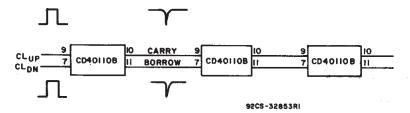
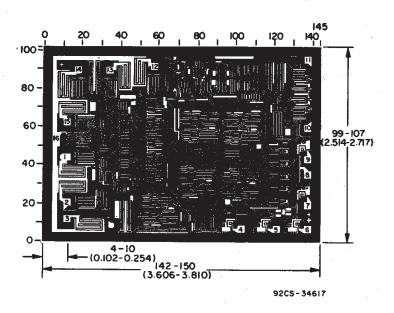


Fig. 15 - Cascading diagram.



Dimensions and pad layout for CD40110B.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10⁻³ inch).

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